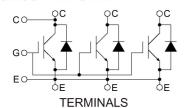
MBN1500E33D

PRELIMINARY SPEC.

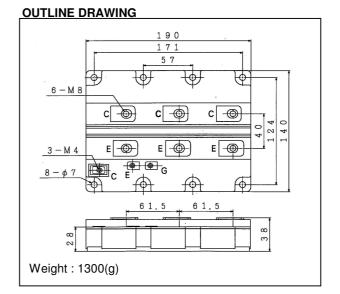
Silicon N-channel IGBT

FEATURES

- * High speed, low loss IGBT module.
- * Low driving power due to low input capacitance MOS gate.
- * Low noise due to ultra soft fast recovery diode.
- * High reliability, high durability module.
- * High thermal fatigue durability. (delta Tc=70K, N>30,000cycles)
- * Isolated head sink (terminal to base). CIRCUIT DIAGRAM



ABSOLUTE MAXIMUM RATINGS (Tc=25°C)



Item		Symbol	Unit	MBN1500E33D	
Collector Emitter Voltage		$V_{\sf CES}$	V	3,300	
Gate Emitter Voltage		V_{GES}	V	±20	
Collector Current	DC	Ιc	Α	1,500	
Collector Current	1ms	I_{Cp}	A	3,000	
Forward Current	DC	l _F	Α	1,500	
- Orward Gurrent	1ms	I _{FM}	A	3,000	
Junction Temperature		Tj	°C	-40 ~ +125	
Storage Temperature		T_{stg}	°C	-40 ~ +125	
Isolation Voltage		V_{ISO}	V_{RMS}	6,000(AC 1 minute)	
Screw Torque	Terminals (M4/M8)	ı	N∙m	2/10 (1)	
	Mounting (M6)	-	INTII	6 (2)	

Notes: (1) Recommended Value 1.8±0.2/9±1N·m

(2) Recommended Value 5.5±0.5N·m

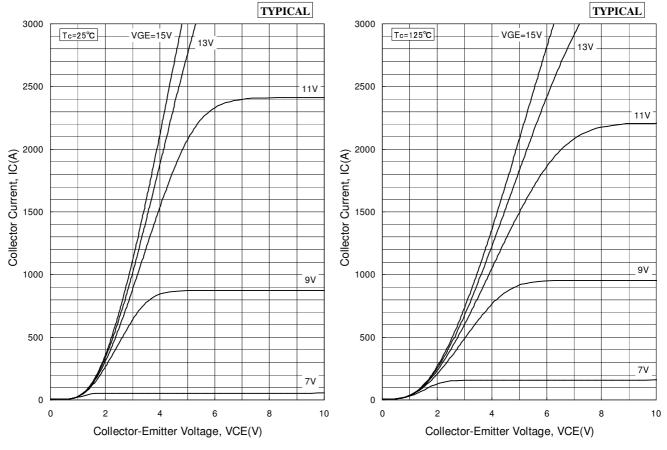
ELECTRICAL CHARACTERISTICS

Item		Symbol	Unit	Min.	Тур.	Max.	Test Conditions
Collector Emitter Cut-Off Current		I _{CES}	mA	-	-	12	V _{CE} =3,300V, V _{GE} =0V, Tj=25°C
				-	20	60	V _{CE} =3,300V, V _{GE} =0V, Tj=125°C
Gate Emitter Leakage Current		I_{GES}	nA	-500	-	+500	$V_{GE}=\pm 20V$, $V_{CE}=0V$, $Tj=25^{\circ}C$
Collector Emitter Saturation Voltage		V _{CE(sat)}	V	-	4.2	tbd	I _C =1,500A, V _{GE} =15V, Tj=125°C
				-	3.8	-	I _C =1,200A, V _{GE} =15V, Tj=125°C
Gate Emitter Threshold Voltage		$V_{GE(TO)}$	V	4.5	6.0	7.0	V _{CE} =10V, I _C =1,500mA, Tj=25°C
Input Capacitance		C_ies	nF	-	105	-	$V_{CE}=10V, V_{GE}=0V, f=100kHz, Tj=25^{\circ}C$
Internal Gate Resistance		Rge	Ω	-	0.8	-	$V_{CE}=10V$, $V_{GE}=0V$, $f=100kHz$, $Tj=25$ °C
Switching Times	Rise Time	t _r	μs	-	1.6	tbd	V _{CC} =1,650V, Ic=1,500A
	Turn On Time	t _{on}		-	2.3	tbd	L=75nH
	Fall Time	t _f		-	1.2	tbd	$R_{G}=2.2\Omega/2.2\Omega$, CGE=330nF (3)
	Turn Off Time	t _{off}		-	3.3	tbd	$V_{GE}=\pm 15V, T_{J}=125^{\circ}C$
Peak Forward Voltage Drop		V_{FM}	V	-	2.7	tbd	Ic=1,500A, V _{GE} =0V, Tj=125°C
				-	2.4	-	Ic=1,200A, V _{GE} =0V, Tj=125°C
Reverse Recovery Time		t _{rr}	μs	-	0.7	tbd	Vcc=1,650V, lc=1,500A, L=75nH Tj=125°C
Turn On Loss		E _{on(10%)}	J/P	-	2.0	tbd	V _{CC} =1,650V, Ic=1,500A, L=75nH
Turn Off Loss		E _{off(10%)}	J/P	-	1.5	tbd	$R_G=2.2\Omega/2.2\Omega$, CGE=330nF (3)
Reverse Recovery Loss		E _{rr(10%)}	J/P	-	1.3	tbd	V _{GE} =±15V, Tj=125°C
Stray inductance module		LSCE	nΗ	-	12	-	
Thermal Impedance	IGBT	Rth(j-c)	K/W	-	-	0.0078	Junction to case
	FWD	Rth(j-c)		-	-	0.0156	
Contact Thermal Impedance		Rth(c-f)	K/W	-	0.006		Case to fin

Notes:(3) R_G value is the test condition's value for evaluation of the switching times, not recommended value. Please, determine the suitable R_G value after the measurement of switching waveforms (overshoot voltage, etc.) with appliance mounted.

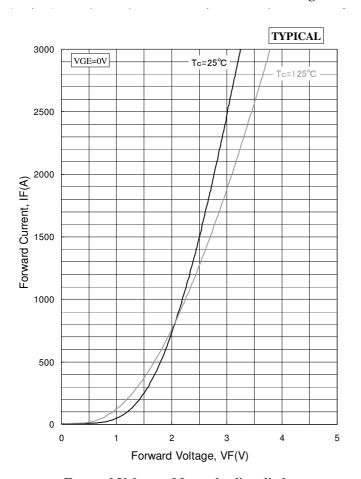
- * Please contact our representatives at order.
- * For improvement, specifications are subject to change without notice.
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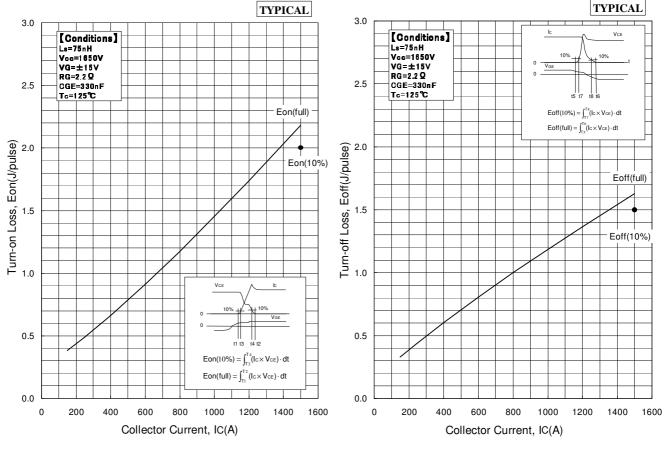
Collecter Current vs. Collector to Emitter Voltage





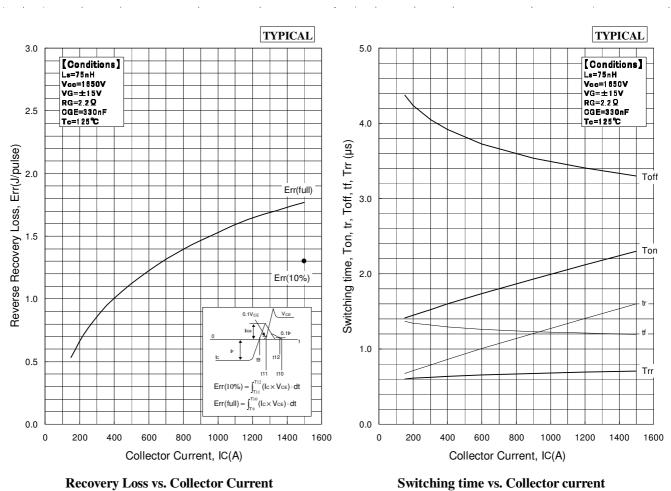
Forward Voltage of free-wheeling diode



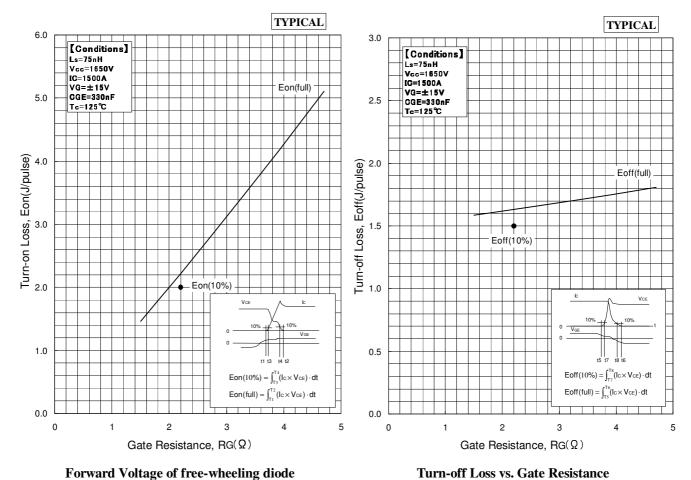


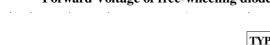
Forward Voltage of free-wheeling diode

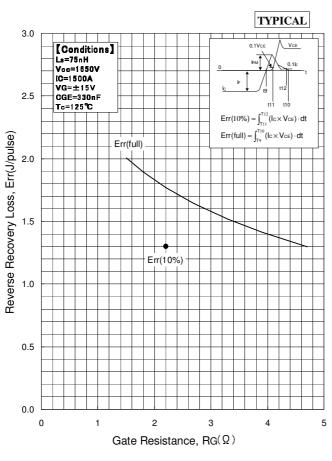








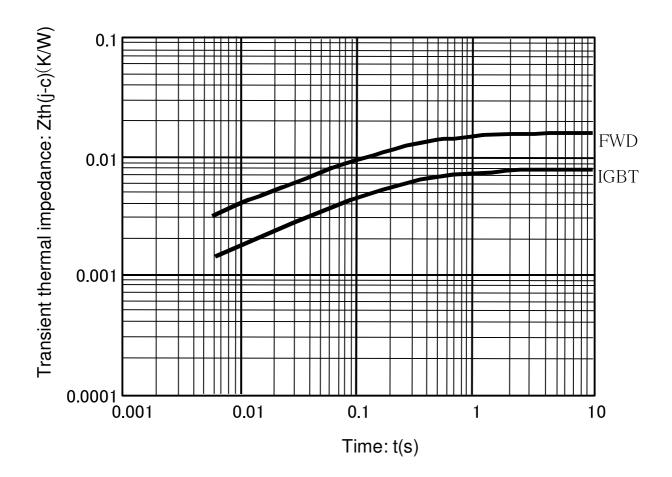




Recovery Loss vs. Gate Resistance



Maximum



Transient Thermal Impedance Curve



HITACHI POWER SEMICONDUCTORS

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